

## AMENDMENTS

### IN THE CLAIMS

Claims 1-280. (canceled)

281. (previously added) A method for fabricating an electronic component, comprising:  
joining a die and a substrate, wherein said die has a top surface at a horizontal level; and  
after said joining said die and said substrate, depositing a bump over said horizontal level,  
wherein said bump comprises gold.

282. (currently amended) A method for fabricating an electronic component, comprising:  
~~providing a die having a top surface at a horizontal level;~~  
depositing an insulating ~~insulation~~-layer over ~~a die said horizontal level~~, wherein said  
insulating ~~insulation~~-layer comprises a porous structure, ~~;~~ and  
~~depositing a metal layer over said horizontal level.~~

283. (currently amended) A method for fabricating an electronic component, comprising:  
~~providing joining a die and a substrate, wherein said die has having a top surface at a~~  
~~horizontal level; and~~  
~~depositing a metal layer over said top surface and extending to a place not over said die;~~  
and

after said joining said die and said substrate, depositing a passive device over said  
horizontal level.

284. (previously added) A method for fabricating an electronic component, comprising:  
providing a die having a top surface at a horizontal level; and  
depositing a waveguide over said horizontal level.

285. (previously added) A method for fabricating an electronic component, comprising:  
providing a die having a top surface at a horizontal level; and  
depositing a micro electronic mechanical sensor (MEMS) over said horizontal level.

286. (currently amended) A method for fabricating an electronic component, comprising:  
~~providing a substrate comprising an organic material;~~  
~~joining multiple dies with said substrate;~~  
depositing an insulating layer over a circuitry element;  
grinding said insulating layer; and  
depositing a metal layer over said insulating layer. ~~multiple dies, wherein said depositing~~  
~~said metal layer comprises electroplating; and~~  
~~cutting said substrate.~~